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## \*BIBDATASHEET\*

Bib Data Sheet

**CONFIRMATION NO. 4031** 

SERIAL NUMB 10/693,896	FILING OR 371(c) DATE 10/693,896 10/28/2003 RULE		CLASS 438		GROUP ART UNIT 2813		ATTORNEY DOCKET NO. CHEN3595/EM		
Su Tao, Ka	aohsiu	en, Jubei City, TAIWAN ing, TAIWAN;							
** FOREIGN APPLICATIONS ************************************									
Foreign Priority claimed yes no  35 USC 119 (a-d) conditions yes no Met after Allowance  Verified and Acknowledged Examiner's Signature Initials				STATE OR COUNTRY TAIWAN	SHEETS DRAWING 5		TOTAL CLAIMS 13		INDEPENDENT CLAIMS 1
ADDRESS 23364									
TITLE  Wafer bumping process with solder balls bonded to under bump metallurgy layer formed over active surface by forming flux on solder ball surfaces and reflowing the solder									
RECEIVED						All Fees  1.16 Fees (Filing)  1.17 Fees (Processing Ext. of time)  1.18 Fees (Issue)  Other  Credit			